

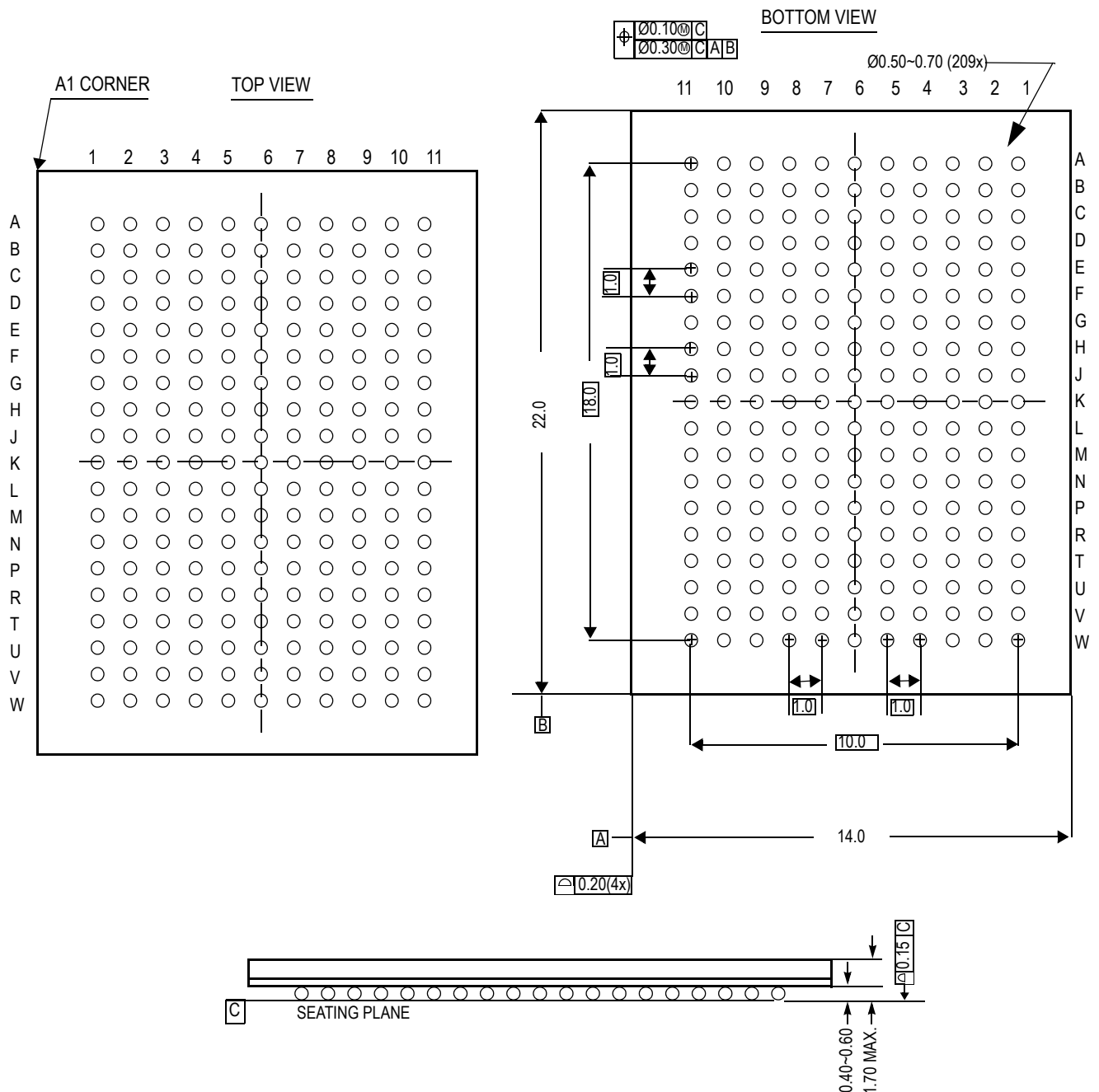
209-Bump BGA (14 mm x 22 mm) Daisy Chain Package

Description

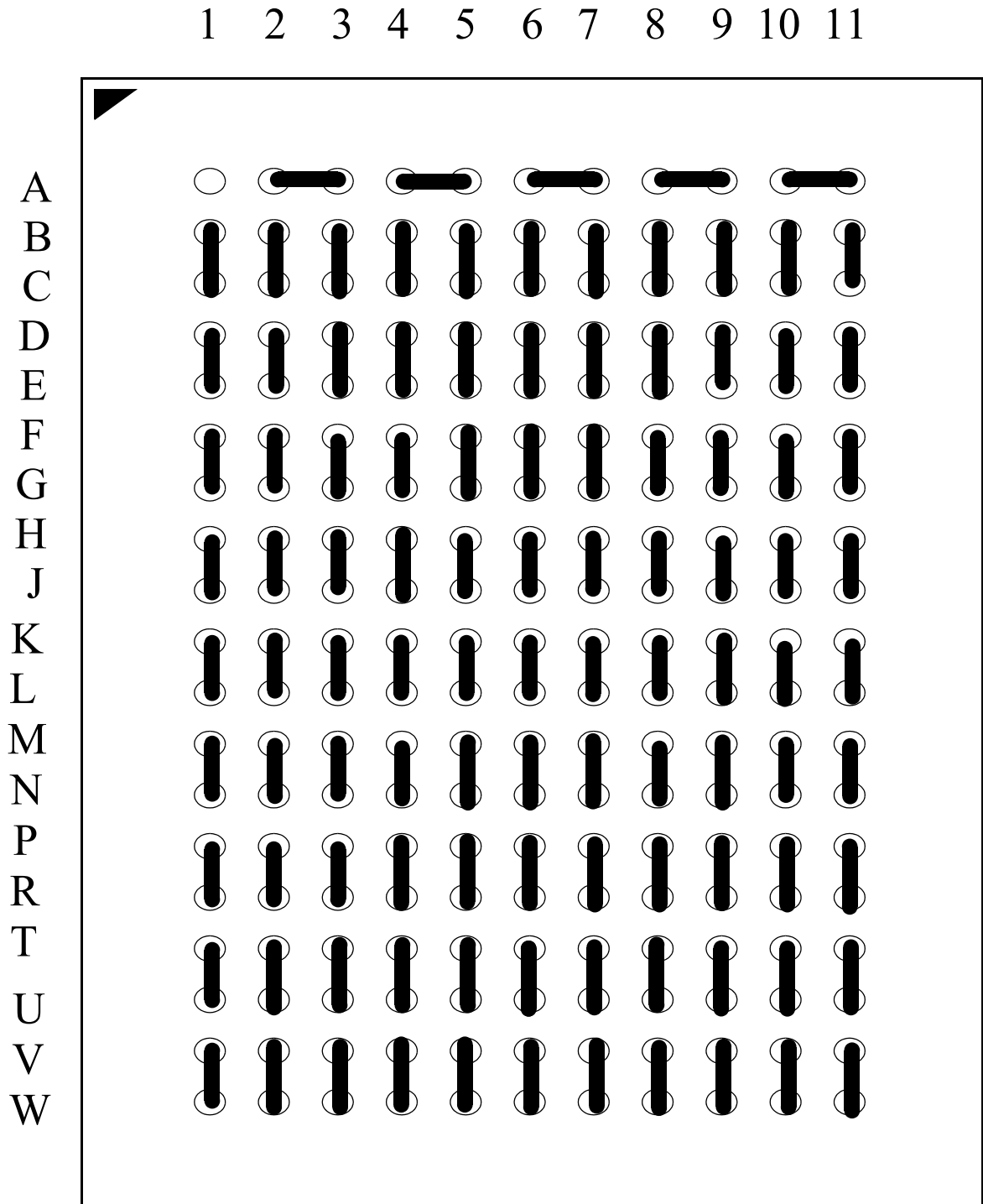
This mechanical daisy chain test vehicle is designed to represent the 209-Bump BGA package. It is used for second level interconnect assembly test and continuity verification.

Package Dimensions—209-Bump BGA (Package C)

14 mm x 22 mm Body, 1.0 mm Bump Pitch, 11 x 19 Bump Array



209 BGA Interconnection Diagram

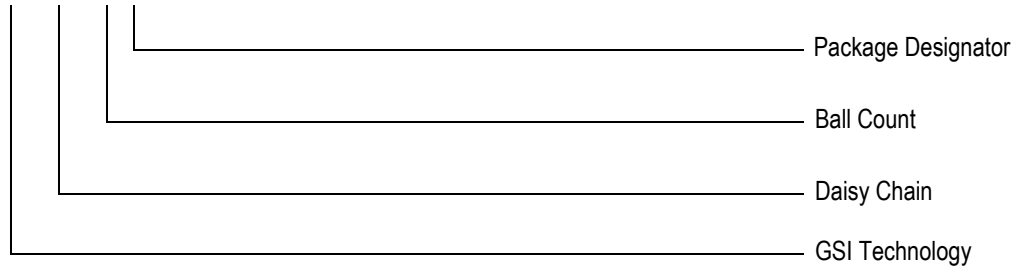


Ordering Information

209-Bump BGA (14 mm x 22 mm)

Daisy Chain Package

GSDC209C



209-Bump BGA (14 mm x 22 mm)

Daisy Chain Package
RoHS-compliant Option

GSDC209GC

